

次世代PKG基板用の 高信頼性穴埋めインキ!

High-Reliability Hole Plugging Ink for PKG Substrate of Next Generation

08

熱硬化型穴埋めインキ THP-100 DX Series

Thermal Cure Hole Plugging Ink

特長 Features

■ 高Tg/低CTE

High Tg/Low CTE

■ TCT耐性良好

Excellent anti crack resistance at TCT

-65deg.C ⇔ 150deg.C / 1000cycle / No crack

■ リフロー耐性良好

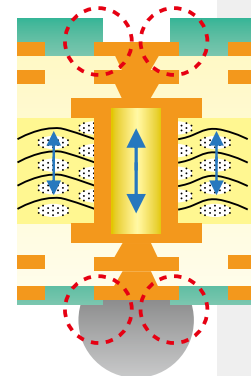
Excellent anti crack resistance at reflow

特性 Properties

	従来品 Conventional product	THP-100 DX7 Mass-produced	THP-100 DX9 Development Product	Test Condition
粘度 (dPa·s)	450±50	450±50	450±50	コーンプレート型粘度計 Cone plate type viscometer
ガラス転移温度(deg.C) Tg	150-160	165-175	175-185	TMA (Pulling mode) X-Y方向 X-Y direction
線膨張係数(ppm) CTE(α1/α2)	30-35 / 100-110	20-25 / 55-65	10-15 / 40-50	

	従来品 Conventional product	THP-100 DX7
Before Reflow		
L2a (C-120/60/60) + Reflow (270deg.C/5cycles)		

- ① Core T=0.4mm PTH=0.25mm
 - ② Treatment
L2a(C120/60/60)
+Reflow(270deg.C/5cycles)
- ※基板表面実温度



用途 Application

■ THP-100 DX7: 現行PKG、通信、車載基板
PKG Substrate, Server, Automotive

■ THP-100 DX9: 次世代PKG基板
PKG Substrate of Next Generation